PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
Toshiyuki NAKAGAWA	05/14/2007
Hiroyuki INO	05/14/2007
Tomoyuki HIURA	05/14/2007
Tomohiro IKEGAMI	05/15/2007
Masaaki HARA	05/28/2007
Norihito MIHOTA	05/14/2007
Shinichi FUKUDA	05/15/2007
Yoshihiko DEOKA	05/17/2007
Hidetoshi HONDA	05/22/2007

RECEIVING PARTY DATA

Name:	SONY CORPORATION
Street Address:	1-7-1 Konan
Internal Address:	Minato-ku
City:	Tokyo
State/Country:	JAPAN

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	11726233

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CORRESPONDENCE DATA

Fax Number: (312)704-8137
Correspondence will be sent via US Mail when the fax attempt is unsuccessful.
Phone: (312) 277-2006
Email: dayala@rdlklaw.com
Correspondent Name: Robert J. Depke
Address Line 1: ROCKEY, DEPKE, LYONS & KITZINGER LLC
Address Line 2: 233 S. Wacker Drive, Suite 5450

Address Line 4:	Chicago, ILLINOIS 60606
ATTORNEY DOCKET NUMBER:	075834.00993
NAME OF SUBMITTER:	Robert J. Depke

Total Attachments: 3
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Docket Number: 075834.00993

ASSIGNMENT

WHEREAS, I, as a below named inventor, residing at the address stated next to my name, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in

MAGNETIC RECORDING AND REPRODUCTION METHOD, RECORDING APPARATUS, REPRODUCTION APPARATUS AND MAGNETIC RECORDING MEDIUM

for which an application for Letters Patent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, Sony Corporation, a Japanese corporation, with offices at 1-7-1 Konan, Minato-ku, Tokyo, Japan (hereinafter referenced as ASSIGNEE) is desirous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREFORE, in consideration of the sum of One Dollar ($1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, I, as a sole or joint inventor as indicated below, do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, the entire right, title and interest in the said invention, said application, including any divisions and continuations as well as any reissues and reexaminations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, which may be granted for said invention, and in and to any and all priority rights and/or convention rights under the International Convention for the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruing or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto;

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters Patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense;

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

And I hereby authorize and request my attorney(s) of record in this application to insert the serial number and filing date of this application in the spaces that follow:

Application No. 11/726,233 Filing Date: March 21, 2007

This assignment executed on the dates indicated below.

Toshiyuki NAKAGAWA
Name of first or sole inventor Execution date of U.S. Patent Application

Kanagawa, Japan
Residence of first or sole inventor

Toshiyuki Nakagawa May 14, 2007
Signature of First or sole inventor Date of this Assignment

Hiroyuki INO

Name of second inventor — Execution date of U.S. Patent Application

Tokyo, Japan

Residence of second inventor

Hiroyuki Ino — May 14, 2007

Signature of second inventor — Date of this Assignment

Tomoyuki HIURA

Name of third inventor — Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of third inventor

Tomoyuki Hiura — May 14, 2007

Signature of third inventor — Date of this Assignment

Tomohiro IKEGAMI

Name of fourth inventor — Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of fourth inventor

Tomohiro Ikegami — May 15, 2007

Signature of fourth inventor — Date of this Assignment

Masaaki HARA

Name of fifth inventor — Execution date of U.S. Patent Application

Tokyo, Japan

Residence of fifth inventor

Masaaki Hara — May 28, 2007

Signature of fifth inventor — Date of this Assignment

Norihito MIHOTA

Name of sixth inventor — Execution date of U.S. Patent Application

Saitama, Japan

Residence of sixth inventor

Norihito Mihota — May 14, 2007

Signature of sixth inventor — Date of this Assignment

Shinichi FUKUDA

Name of seventh inventor — Execution date of U.S. Patent Application

Kanagawa, Japan

Residence of seventh inventor

Shinichi Fukuda — May 15, 07

Signature of seventh inventor — Date of this Assignment

Yoshihiko DEOKA

Name of eighth inventor — Execution date of U.S. Patent Application

Tokyo, Japan

Residence of eighth inventor

Signature of eighth inventor Yoshihiko Deoka — May 17, 2007 Date of this Assignment

Hidetoshi HONDA

Name of ninth inventor — Execution date of U.S. Patent Application

Miyagi, Japan — May. 22, 2007

Residence of ninth inventor

Signature of ninth inventor Hidetoshi Honda — ~~May. 17, 2007~~ Date of this Assignment

May. 22, 2007 H.H